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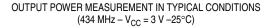
What is "Embedded - Microcontrollers"?

"Embedded - Microcontrollers" refer to small, integrated circuits designed to perform specific tasks within larger systems. These microcontrollers are essentially compact computers on a single chip, containing a processor core, memory, and programmable input/output peripherals. They are called "embedded" because they are embedded within electronic devices to control various functions, rather than serving as standalone computers. Microcontrollers are crucial in modern electronics, providing the intelligence and control needed for a wide range of applications.

Applications of "<u>Embedded - Microcontrollers</u>"

Product Status Obsolete Core Processor HC08 Core Size 8-Bit Speed 4MHz Connectivity - Peripherals LVD, POR, PWM, RF Mod Number of I/O 12 Program Memory Size 2KB (2K x 8) Program Memory Type FLASH EEPROM Size - RAM Size 128 x 8 Voltage - Supply (Vcc/Vdd) 1.8V ~ 3.6V Data Converters - Oscillator Type Internal Operating Temperature -40°C ~ 85°C (TA) Mounting Type Surface Mount Package / Case 32-LQFP Supplier Device Package 32-LQFP (7x7)	- · ·	
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EEPROM Size - 128 x 8 Voltage - Supply (Vcc/Vdd) 1.8V ~ 3.6V Data Converters - Oscillator Type Internal Operating Temperature -40°C ~ 85°C (TA) Mounting Type Surface Mount Package / Case 32-LQFP Supplier Device Package 32-LQFP (7x7)	Program Memory Size	2KB (2K x 8)
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Voltage - Supply (Vcc/Vdd) 1.8V ~ 3.6V Data Converters - Oscillator Type Internal Operating Temperature -40°C ~ 85°C (TA) Mounting Type Surface Mount Package / Case 32-LQFP Supplier Device Package 32-LQFP (7x7)	EEPROM Size	-
Data Converters - Oscillator Type Internal Operating Temperature -40°C ~ 85°C (TA) Mounting Type Surface Mount Package / Case 32-LQFP Supplier Device Package 32-LQFP (7x7)	RAM Size	128 x 8
Oscillator Type Internal Operating Temperature -40°C ~ 85°C (TA) Mounting Type Surface Mount Package / Case 32-LQFP Supplier Device Package 32-LQFP (7x7)	Voltage - Supply (Vcc/Vdd)	1.8V ~ 3.6V
Operating Temperature -40°C ~ 85°C (TA) Mounting Type Surface Mount Package / Case 32-LQFP Supplier Device Package 32-LQFP (7x7)	Data Converters	-
Mounting Type Surface Mount Package / Case 32-LQFP Supplier Device Package 32-LQFP (7x7)	Oscillator Type	Internal
Package / Case 32-LQFP Supplier Device Package 32-LQFP (7x7)	Operating Temperature	-40°C ~ 85°C (TA)
Supplier Device Package 32-LQFP (7x7)	Mounting Type	Surface Mount
- 11 - 1 - 1 - 1 - 1 - 1 - 1 - 1 - 1 -	Package / Case	32-LQFP
Purchase URL https://www.e-xfl.com/product-detail/nxp-semiconductors/mchc908rf2cfae	Supplier Device Package	32-LQFP (7x7)
	Purchase URL	https://www.e-xfl.com/product-detail/nxp-semiconductors/mchc908rf2cfae

Electrical Specifications



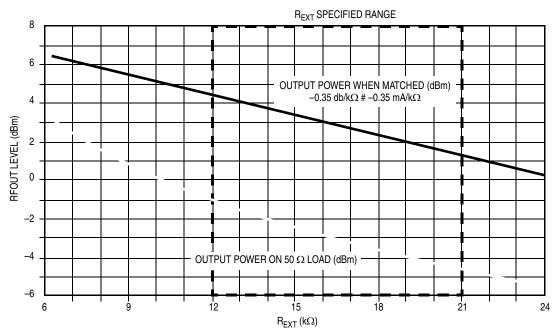


Figure 14-6. Output Power at 434-MHz Frequency Band versus R_{EXT} Value

14.9 Control Timing

Characteristic ⁽¹⁾	Symbol	Min	Max	Unit
Bus operating frequency $V_{DD} = 3.0 \text{ V} \pm 10\%$ $V_{DD} = 2.0 \text{ V} \pm 10\%$	f _{Bus}	32 k 32 k	4.0 M 2.0 M	Hz
RESET pulse width low	t _{RL}	1.5	_	t _{cyc}
IRQ interrupt pulse width low (edge-triggered)	t _{ILHI}	1.5	_	t _{cyc}
IRQ interrupt pulse period	t _{ILIL}	Note 4	_	t _{cyc}
16-bit timer ⁽²⁾ Input capture pulse width ⁽³⁾ Input capture period Input clock pulse width	t _{TH,} t _{TL} t _{TLTL} t _{TCH} , t _{TCL}	2 Note ⁽⁴⁾ (1/f _{OP}) + 5		t _{cyc} t _{cyc} ns

- 1. V_{DD} = 1.8 V to 3.3 V, V_{SS} = 0 Vdc, T_A = -40°C to +85°C, unless otherwise noted 2. The 2-bit timer prescaler is the limiting factor in determining timer resolution.
- 3. Refer to Table 11-3. Mode, Edge, and Level Selection and supporting note.
- 4. The minimum period t_{TLTL} or t_{ILIL} should not be less than the number of cycles it takes to execute the capture interrupt service routine plus 2 t_{cvc}.

MC68HC908RF2 — Rev. 4.0 **Data Sheet**

Electrical Specifications

14.12 Memory Characteristics

Characteristic	Symbol	Min	Тур	Max	Unit
RAM data retention voltage	V _{RDR}	1.3	_	_	V
FLASH pages per row	_	8	_	8	Pages
FLASH bytes per page	_	1	_	1	Bytes
FLASH read bus clock frequency	f _{Read} ⁽¹⁾	32 K	_	2.5 M	Hz
FLASH charge pump clock frequency (See 2.5.2 FLASH 2TS Charge Pump Frequency Control)	f _{Pump} ⁽²⁾	1.8	_	2.5	MHz
FLASH block/bulk erase time	t _{Erase}	100	_	_	ms
FLASH row erase time	t _{RowErase}	30	_	_	ms
FLASH high voltage kill time	t _{Kill}	200	_	_	μs
FLASH return to read time	t _{HVD}	50	_	_	μS
FLASH page program pulses	fls _{Pulses} ⁽³⁾	_	_	15	Pulses
FLASH page program step size	t _{Step} ⁽⁴⁾	1.0	_	1.2	ms
FLASH cumulative program time per row between erase cycles	t _{Row} (5)	_	_	8	Page program cycles
FLASH HVEN low to MARGIN high time	t _{HVTV}	50	_	_	μS
FLASH MARGIN high to PGM low time	t _{VTP}	150	_	_	μs
FLASH 2TS row program endurance ⁽⁶⁾	_	10 ⁴	-		Cycles
FLASH data retention time ⁽⁷⁾	_	15	100		Years

- 1. $f_{\mbox{Read}}$ is defined as the frequency range for which the FLASH memory can be read.
- 2. f_{Pump} is defined as the charge pump clock frequency required for program, erase, and margin read operations.
- 3. fls_{Pulses} is defined as the number of pulses used to program the FLASH using the required smart program algorithm.
- 4. t_{Step} is defined as the amount of time during one page program cycle that HVEN is held high.
- 5. t_{Row} is defined as the cumulative time a row can see the program voltage before the row must be erased before further programming.
- The minimum row endurance value specifies each row of the FLASH 2TS memory is guaranteed to work for at least this many erase/program cycles.
- 7. The FLASH is guaranteed to retain data over the entire temperature range for at least the minimum time specified.